Innovative Materials Manufacturer

Dispensable Thermal Conductive Gel Series

[Thermal Gap filler]

DATA SHEET



- Product picture -

The Dispensable Thermal Gel cures to a flexible rubber elastomer and suit for the protection of electrical/electronic applications where heat dissipation is very importand. In particular, it is suitable when the different components share a radiator. It can be automatedly dispensed and realize automatic production. The Dispensable Thermal Gel will not pollute the Component because it is easy to peel after curing and rework.

FEATURES:

- High thermal conductivity, low thermal resistance
- Use dispensable pad to replace traditional fabricated pad
- Being capable of printed through a variety of manual or automated process
- Can be dispensed or printed through a variety of manual or automated process
- Can be dispensed or coated into a variety of thickness and shapes
- Soft, relieving stress and shock mitigation
- Desired thickness is maintained after curing

APPLICATIONS:

- Semiconductor and radiators
- Cooling electronic devices in LED lamps, luminaries, automotive and consumer electronics
- Being dispensed or coated into a variety of thicknesses and shapes
- CPU and GPU

APPLICATION METHODS:

• Dispensable Thermal Gel is designed to be applied by various methods including automated dispensing, stencil printing and Manual coating.

The series of products are accord with standards

STORAGE TEMPERATURE:0~10°C **SHELF LIFE:**1 years(@4°C)

Items	Parameter	Unit	Test Method
	HTDG-250		
Appearance	White pasty substance	-	Visual
Density	2.6(±0.5)	g/cm³	ASTM D 792
Hardness	30(±5)	Shore C	ASTM D 2240
Tensile Strength	≥0.4	Мра	ASTM D 412
Elongation	≥200	%	ASTM D 412
Curing Time	120(50℃),55(70℃),25(120℃)	min	-
50% Instantaneous compressive stress	<10	Psi	GB/T 7757-2009
50% Static compressive stress	<1	Psi	GB/T 7757-2009
Adhesive force	<15	Psi	-
UL Certification	V0	-	UL94
Operating Temperature	-50~150	℃	
THERMAL CHARACTERISTIC			
Thermal Conductivity	2.5(±0.2)	W/m·K	ASTM D 5470
ELECTRICAL PROPERTIES			
Breakdown Voltage	≥8(@1.5mm)	KV	ASTM D 149

≥1.0*10¹³

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ASTM D 257

CURED. STORAGE CONDITIONS:

• It will be completely cured for about 72 hours at room temperature. The viscosity of the Dispensable Thermal Gel does not change within 8 hours, but it begins to cure by a gradual increase in viscosity after 8 hours, followed by gelation and conversion to its final elastomeric state.

Volume Resistivity

• In order to ensure the stability of product performance, it should be stored at a temperature of less than 4 ° C (including 4 °C). If the product can't be completely used, the unused product should be sealed and refrigerated at temperatures below 4 °C (including 4 °C) so that it can be re-used, but the overall operating time is 8 hours or less than 8 hours.

PACKING SPECIFICATIONS:

• 30cc/55cc/300cc

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PROPERTIES